Final datasheet

EasyDUAL module with CoolSiC™ Trench MOSFET and PressFIT / NTC / TIM

Features


Typical appearance

- Electrical features
  - V_{DSS} = 1200 V
  - I_{DN} = 150 A / I_{DRM} = 300 A
  - Low switching losses
  - Low inductive design
  - High current density
  - Suitable Infineon gate drivers can be found under https://www.infineon.com/gdfinder
- Mechanical features
  - Rugged mounting due to integrated mounting clamps
  - PressFIT contact technology
  - Integrated NTC temperature sensor
  - Pre-applied thermal interface material

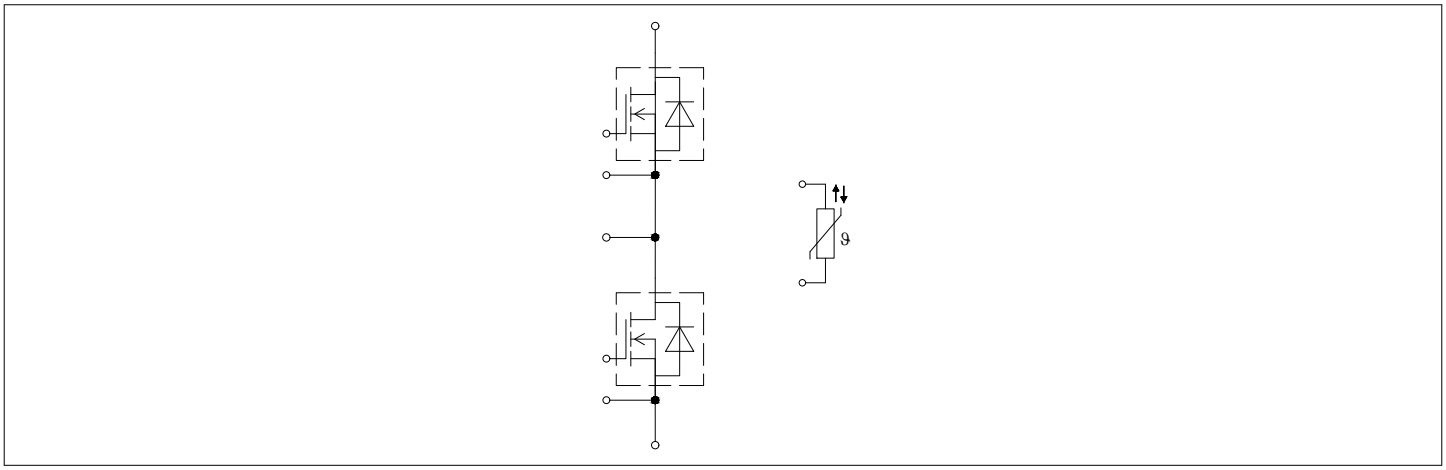
Potential applications

- UPS systems
- High-frequency switching application
- DC/DC converter
- Solar applications

Product validation

- Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

Description



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1 Package

Table 1 Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, f = 50 Hz, *t* = 1 min	3.0	kV
Isolation test voltage NTC	$V_{ISOL(NTC)}$	RMS, f = 50 Hz, *t* = 1 min	3.0	kV
Internal isolation		basic insulation (class 1, IEC 61140)	Al_2O_3	
Comparative tracking index	*CTI*		> 200	
Relative thermal index (electrical)	*RTI*	housing	140	°C

Table 2 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Stray inductance module	L_{sCE}			8		nH
Module lead resistance, terminals - chip	$R_{CC'+EE'}$	T_H = 25 °C, per switch		1.4		mΩ
Storage temperature	T_{stg}		-40		125	°C
Maximum baseplate operation temperature	T_{BPmax}				125	°C
Mounting force per clamp	*F*		40		80	N
Weight	*G*			39		g

***Note**: The current under continuous operation is limited to 25 A rms per connector pin.*
Storage and shipment of modules with TIM => see AN 2012-07

2 MOSFET

Table 3 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Drain-source voltage	V_{DSS}		T_{vj} = 25 °C	1200	V
Continuous DC drain current	I_{DDC}	T_{vj} = 175 °C, V_{GS} = 18 V	T_H = 65 °C	150	A
Repetitive peak drain current	I_{DRM}	verified by design, t_p limited by T_{vjmax}		300	A
Gate-source voltage, max. transient voltage	V_{GS}	*D* < 0.01		-10/23	V
Gate-source voltage, max. static voltage	V_{GS}			-7/20	V

Table 4 Recommended values

Parameter	Symbol	Note or test condition	Values	Unit
On-state gate voltage	$V_{GS(on)}$		15...18	V
Off-state gate voltage	$V_{GS(off)}$		-5...0	V

Table 5 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Drain-source on-resistance	$R_{DS(on)}$	I_D = 150 A	V_{GS} = 18 V, T_{vj} = 25 °C		5.4	8	mΩ
			V_{GS} = 18 V, T_{vj} = 125 °C		8.7		
			V_{GS} = 18 V, T_{vj} = 175 °C		11.6		
			V_{GS} = 15 V, T_{vj} = 25 °C		6.5		
Gate threshold voltage	$V_{GS(th)}$	I_D = 60 mA, V_{DS} = V_{GS}, T_{vj} = 25 °C, (tested after 1ms pulse at V_{GS} = +20 V)		3.45	4.3	5.15	V
Total gate charge	Q_G	V_{DD} = 800 V, V_{GS} = -3/18 V, T_{vj} = 25 °C			0.446		µC
Internal gate resistor	R_{Gint}	T_{vj} = 25 °C			1.4		Ω
Input capacitance	C_{ISS}	f = 100 kHz, V_{DS} = 800 V, V_{GS} = 0 V	T_{vj} = 25 °C		13.2		nF
Output capacitance	C_{OSS}	f = 100 kHz, V_{DS} = 800 V, V_{GS} = 0 V	T_{vj} = 25 °C		0.63		nF
Reverse transfer capacitance	C_{rss}	f = 100 kHz, V_{DS} = 800 V, V_{GS} = 0 V	T_{vj} = 25 °C		0.042		nF
C_{OSS} stored energy	E_{OSS}	V_{DS} = 800 V, V_{GS} = -3/18 V, T_{vj} = 25 °C			258		µJ
Drain-source leakage current	I_{DSS}	V_{DS} = 1200 V, V_{GS} = -3 V	T_{vj} = 25 °C		0.09	530	µA
Gate-source leakage current	I_{GSS}	V_{DS} = 0 V, T_{vj} = 25 °C	V_{GS} = 20 V			400	nA
Turn-on delay time (inductive load)	$t_{d\,on}$	I_D = 150 A, R_{Gon} = 2.7 Ω, V_{DD} = 600 V, V_{GS} = -3/18 V, t_{dead} = 1000 ns, 0.1 V_{GS} to 0.1 I_D	T_{vj} = 25 °C		31		ns
			T_{vj} = 125 °C		31		
			T_{vj} = 175 °C		32		
Rise time (inductive load)	t_r	I_D = 150 A, R_{Gon} = 2.7 Ω, V_{DD} = 600 V, V_{GS} = -3/18 V, t_{dead} = 1000 ns, 0.1 I_D to 0.9 I_D	T_{vj} = 25 °C		13		ns
			T_{vj} = 125 °C		13		
			T_{vj} = 175 °C		14		

(table continues...)

Table 5 (continued) Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Turn-off delay time (inductive load)	$t_{d\,off}$	I_D = 150 A, R_{Goff} = 0.51 Ω, V_{DD} = 600 V, V_{GS} = -3/18 V, 0.9 V_{GS} to 0.9 I_D	T_{vj} = 25 °C		35		ns
			T_{vj} = 125 °C		38		
			T_{vj} = 175 °C		41		
Fall time (inductive load)	t_f	I_D = 150 A, R_{Goff} = 0.51 Ω, V_{DD} = 600 V, V_{GS} = -3/18 V, 0.9 I_D to 0.1 I_D	T_{vj} = 25 °C		11		ns
			T_{vj} = 125 °C		12		
			T_{vj} = 175 °C		16		
Turn-on energy loss per pulse	E_{on}	I_D = 150 A, V_{DD} = 600 V, L_σ = 8 nH, V_{GS} = -3/18 V, R_{Gon} = 2.7 Ω, di/dt = 13.5 kA/µs (T_{vj} = 175 °C), t_{dead} = 1000 ns	T_{vj} = 25 °C		2.12		mJ
			T_{vj} = 125 °C		2.35		
			T_{vj} = 175 °C		2.67		
Turn-on energy loss per pulse, optimized	$E_{on,o}$	I_D = 150 A, V_{DD} = 600 V, L_σ = 8 nH, V_{GS} = -3/18 V, $R_{Gon,o}$ = 1.5 Ω, di/dt = 18.1 kA/µs (T_{vj} = 175 °C), t_{dead} = 100 ns	T_{vj} = 25 °C		1.28		mJ
			T_{vj} = 125 °C		1.3		
			T_{vj} = 175 °C		1.35		
Turn-off energy loss per pulse	E_{off}	I_D = 150 A, V_{DD} = 600 V, L_σ = 8 nH, V_{GS} = -3/18 V, R_{Goff} = 0.51 Ω, dv/dt = 42.5 kV/µs (T_{vj} = 175 °C)	T_{vj} = 25 °C		0.41		mJ
			T_{vj} = 125 °C		0.434		
			T_{vj} = 175 °C		0.445		
SC data	I_{SC}	V_{GS} = -5/15 V, V_{DD} = 800 V, V_{DSmax} = V_{DSS}-L_{sDS}*di/dt, R_G = 10 Ω	t_P = 2 µs, T_{vj} = 25 °C		1260		A
			t_P = 2 µs, T_{vj} = 150 °C		1230		
Thermal resistance, junction to heat sink	R_{thJH}	per MOSFET, Valid with IFX pre-applied Thermal Interface Material				0.314	K/W
Temperature under switching conditions	$T_{vj\,op}$			-40		175	°C

***Note**: The selection of positive and negative gate-source voltages impacts losses and the long-term behavior of the MOSFET and body diode. The design guidelines described in Application Notes AN 2018-09 and AN 2021-13 must be considered to ensure sound operation of the device over the planned lifetime.*

Tvj,op > 150°C is allowed for operation at overload conditions for MOSFET and body diode. For detailed specifications, please refer to AN 2021-13.

3 Body diode (MOSFET)

Table 6 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
DC body diode forward current	I_{SD}	T_{vj} = 175 °C, V_{GS} = -3 V	T_H = 65 °C	85	A

Table 7 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Forward voltage	V_{SD}	I_{SD} = 150 A, V_{GS} = -3 V	T_{vj} = 25 °C		4.2	5.35	V
			T_{vj} = 125 °C		3.9		
			T_{vj} = 175 °C		3.8		
Peak reverse recovery current	I_{rrm}	I_{SD} = 150 A, di_s/dt = 13.5 kA/µs, V_{DD} = 600 V, V_{GS} = -3 V, t_{dead} = 1000 ns	T_{vj} = 25 °C		106		A
			T_{vj} = 125 °C		155		
			T_{vj} = 175 °C		175		
Recovered charge	Q_{rr}	I_{SD} = 150 A, di_s/dt = 13.5 kA/µs, V_{DD} = 600 V, V_{GS} = -3 V, t_{dead} = 1000 ns	T_{vj} = 25 °C		1.36		µC
			T_{vj} = 125 °C		2.47		
			T_{vj} = 175 °C		3.2		
Reverse recovery energy	E_{rec}	I_{SD} = 150 A, di_s/dt = 13.5 kA/µs (T_{vj} = 175 °C), V_{DD} = 600 V, V_{GS} = -3 V, t_{dead} = 1000 ns	T_{vj} = 25 °C		0.521		mJ
			T_{vj} = 125 °C		0.863		
			T_{vj} = 175 °C		1.16		
Reverse recovery energy, optimized	$E_{rec,o}$	I_{SD} = 150 A, di_s/dt = 18.1 kA/µs (T_{vj} = 175 °C), V_{DD} = 600 V, V_{GS} = -3 V, t_{dead} = 100 ns	T_{vj} = 25 °C		0.764		mJ
			T_{vj} = 125 °C		0.816		
			T_{vj} = 175 °C		0.963		

4 NTC-Thermistor

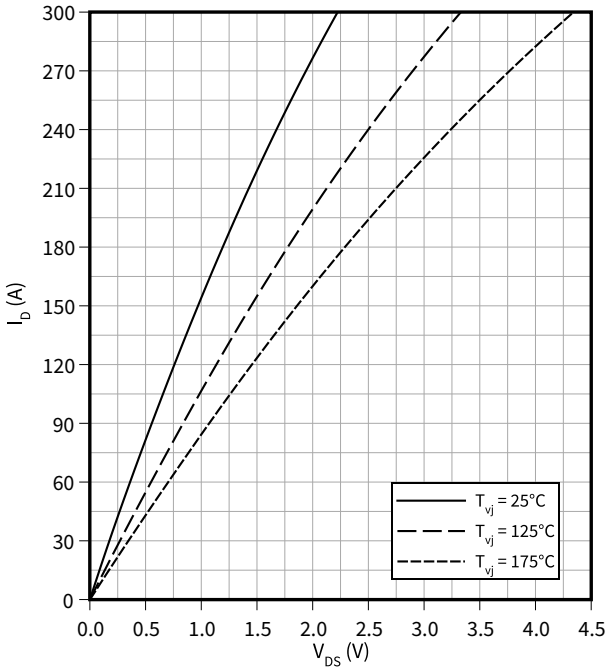
Table 8 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Rated resistance	R_{25}	T_{NTC} = 25 °C		5		kΩ
Deviation of R_{100}	$\Delta R/R$	T_{NTC} = 100 °C, R_{100} = 493 Ω	-5		5	%
Power dissipation	P_{25}	T_{NTC} = 25 °C			20	mW
B-value	$B_{25/50}$	$R_2 = R_{25} \exp[B_{25/50}(1/T_2\text{-}1/(298{,}15\ K))]$		3375		K
B-value	$B_{25/80}$	$R_2 = R_{25} \exp[B_{25/80}(1/T_2\text{-}1/(298{,}15\ K))]$		3411		K
B-value	$B_{25/100}$	$R_2 = R_{25} \exp[B_{25/100}(1/T_2\text{-}1/(298{,}15\ K))]$		3433		K

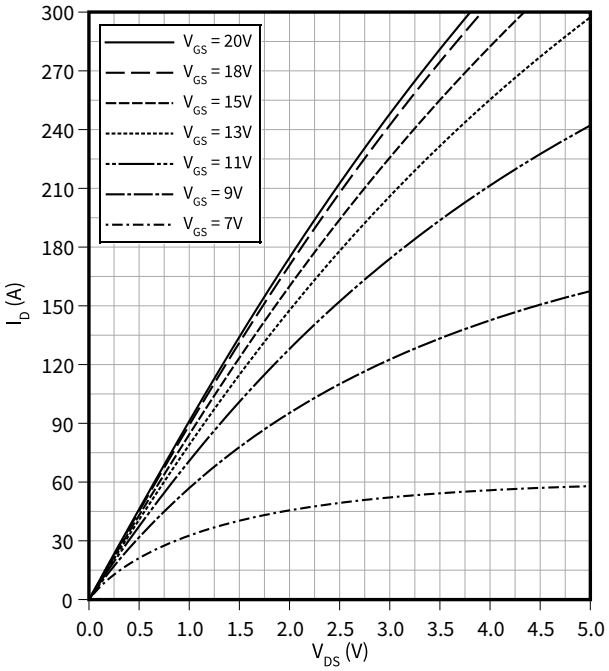
***Note**: For an analytical description of the NTC characteristics please refer to AN2009-10, chapter 4.*

5 Characteristics diagrams

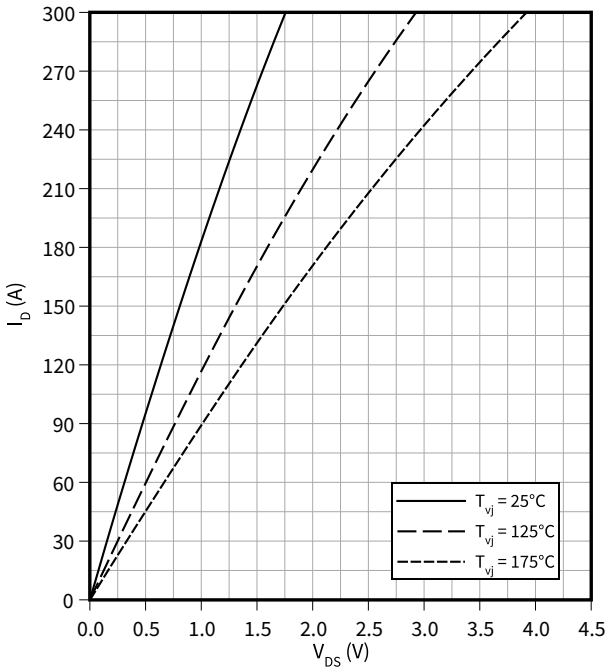
Output characteristic (typical), MOSFET
$I_D = f(V_{DS})$
V_{GS} = 15 V



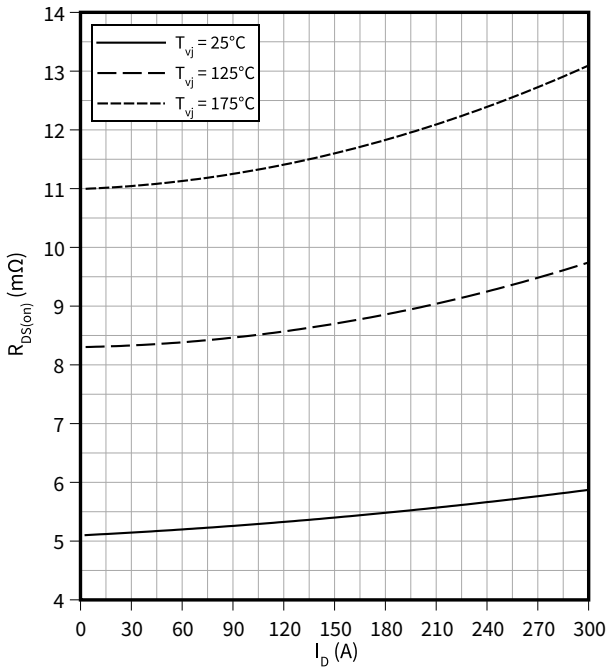
Output characteristic (typical), MOSFET
$I_D = f(V_{DS})$
T_{vj} = 175 °C



Output characteristic (typical), MOSFET
$I_D = f(V_{DS})$
V_{GS} = 18 V



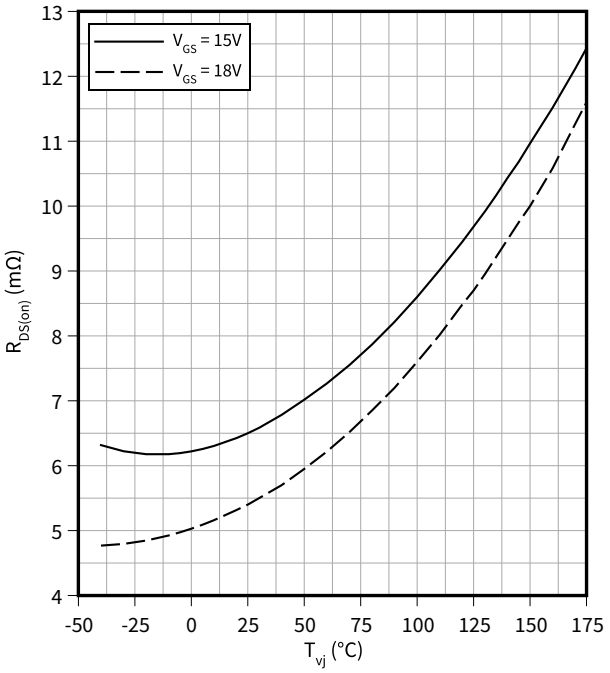
Drain source on-resistance (typical), MOSFET
$R_{DS(on)} = f(I_D)$
V_{GS} =18 V



Drain source on-resistance (typical), MOSFET

$R_{DS(on)} = f(T_{vj})$

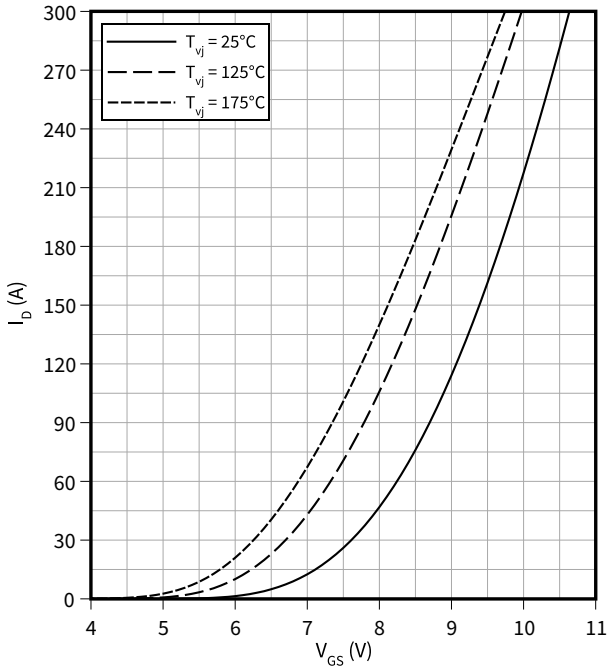
$I_D = 150$ A



Transfer characteristic (typical), MOSFET

$I_D = f(V_{GS})$

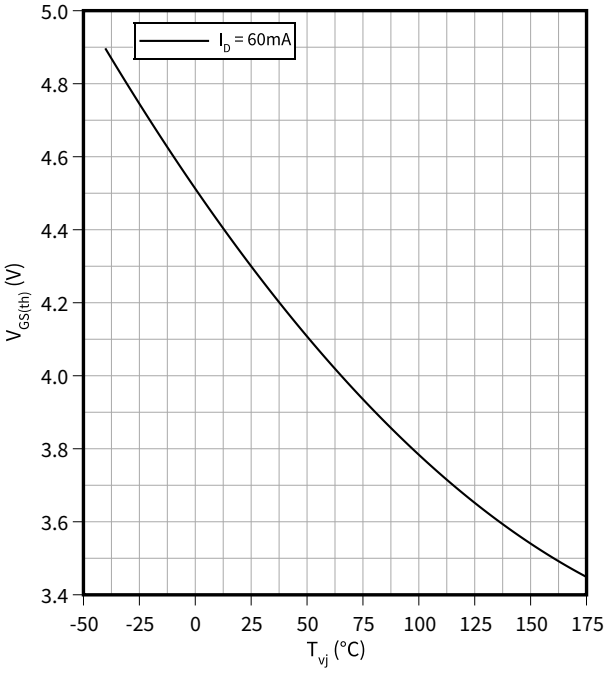
$V_{DS} = 20$ V



Gate-source threshold voltage (typical), MOSFET

$V_{GS(th)} = f(T_{vj})$

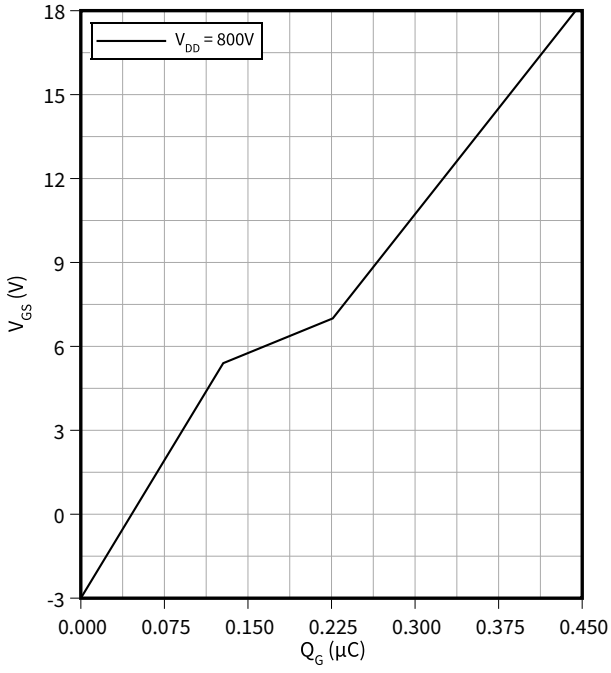
$V_{DS}=V_{GS}$



Gate charge characteristic (typical), MOSFET

$V_{GS} = f(Q_G)$

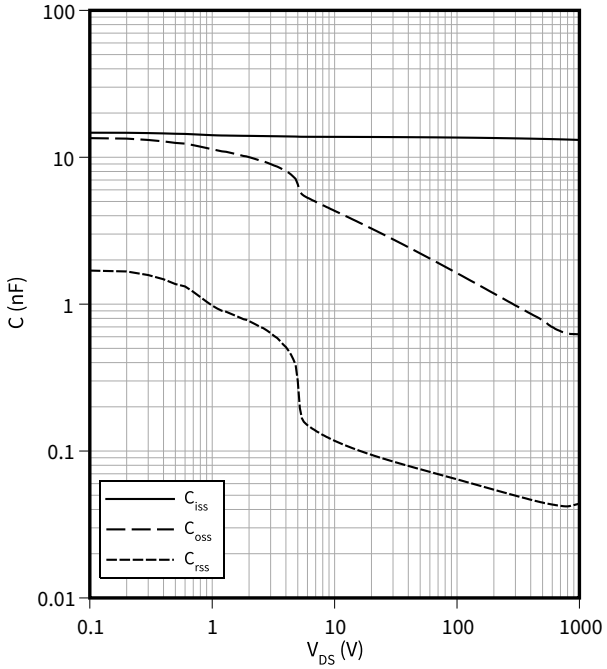
$I_D = 150$ A, $T_{vj} = 25$ °C



Capacity characteristic (typical), MOSFET

$C = f(V_{DS})$

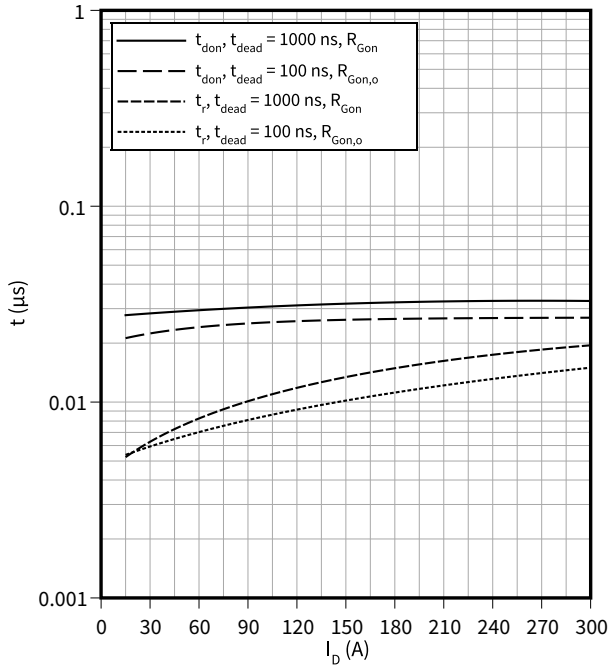
$f = 100$ kHz, $T_{vj} = 25$ °C, $V_{GS} = 0$ V



Switching times (typical), MOSFET

$t = f(I_D)$

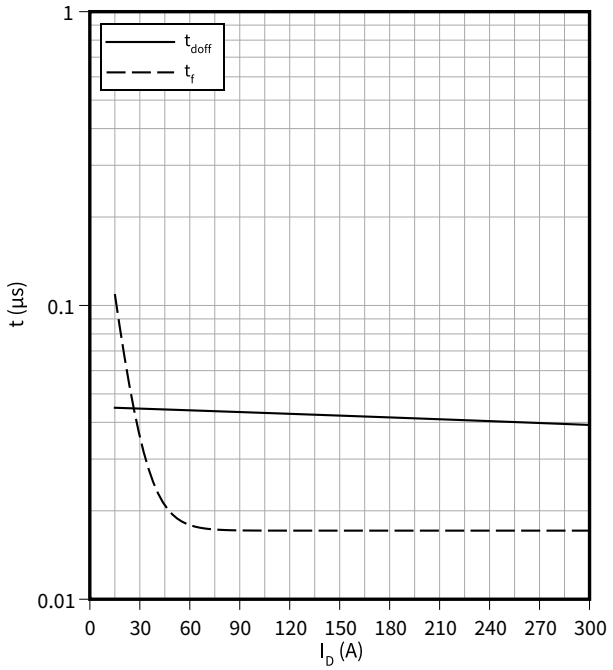
$V_{DD} = 600$ V, $R_{Gon} = 2.7\ \Omega$, $R_{Gon,o} = 1.5\ \Omega$, $T_{vj} = 175$ °C, $V_{GS} = -3/18$ V



Switching times (typical), MOSFET

$t = f(I_D)$

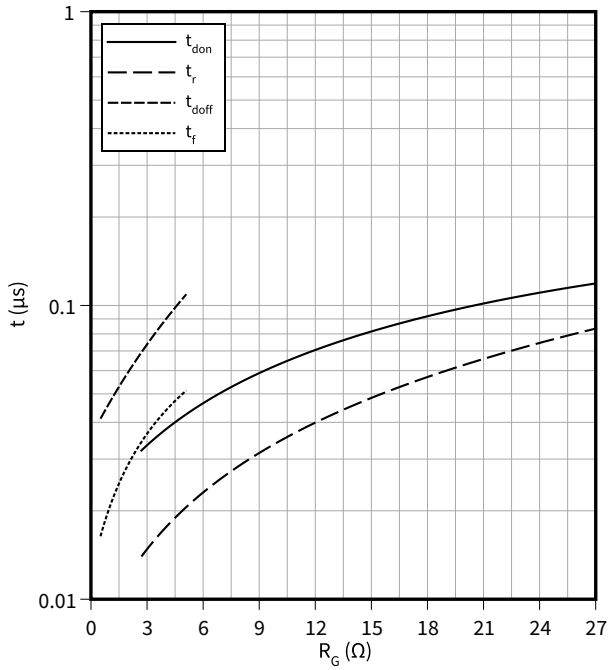
$R_{Goff} = 0.51\ \Omega$, $V_{DD} = 600$ V, $T_{vj} = 175$ °C, $V_{GS} = -3/18$ V



Switching times (typical), MOSFET

$t = f(R_G)$

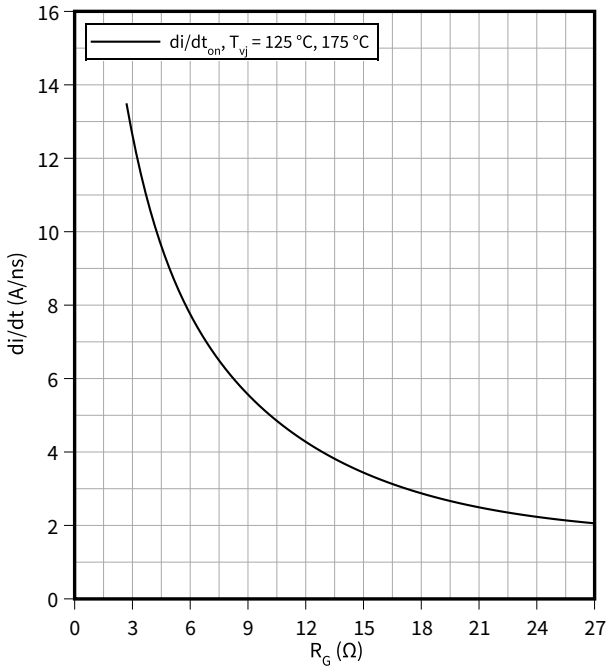
$V_{DD} = 600$ V, $t_{dead} = 1000$ ns, $I_D = 150$ A, $T_{vj} = 175$ °C, $V_{GS} = -3/18$ V



Current slope (typical), MOSFET

$di/dt = f(R_G)$

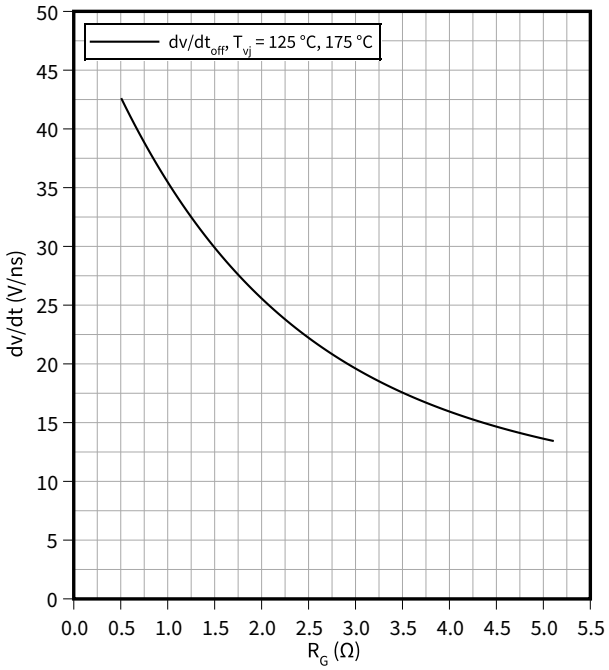
V_{DD} = 600 V, t_{dead} = 1000 ns, I_D = 150 A, V_{GS} = -3/18 V



Voltage slope (typical), MOSFET

$dv/dt = f(R_G)$

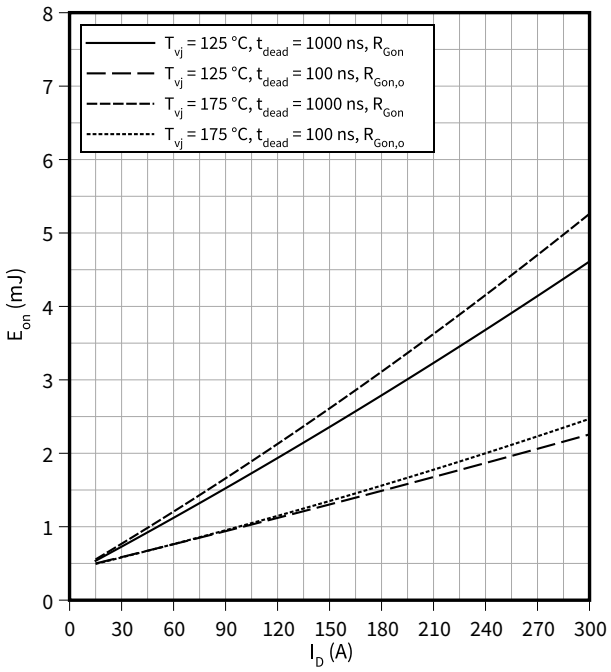
V_{DD} = 600 V, I_D = 150 A, V_{GS} = -3/18 V



Switching losses (typical), MOSFET

$E_{on} = f(I_D)$

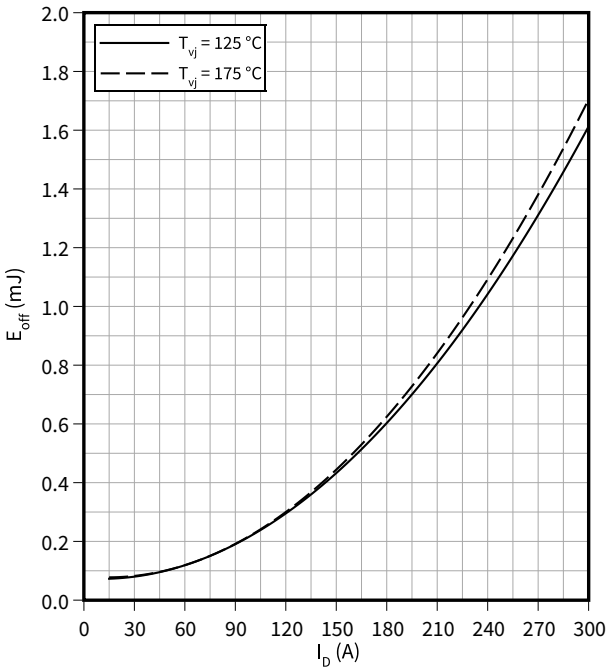
R_{Gon} = 2.7 Ω, V_{DD} = 600 V, $R_{Gon,o}$ = 1.5 Ω, V_{GS} = -3/18 V



Switching losses (typical), MOSFET

$E_{off} = f(I_D)$

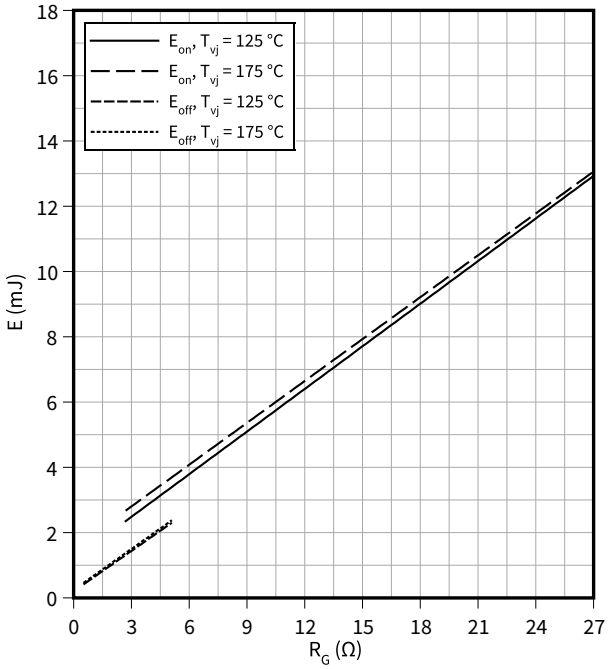
R_{Goff} = 0.51 Ω, V_{DD} = 600 V, V_{GS} = -3/18 V



Switching losses (typical), MOSFET

$E = f(R_G)$

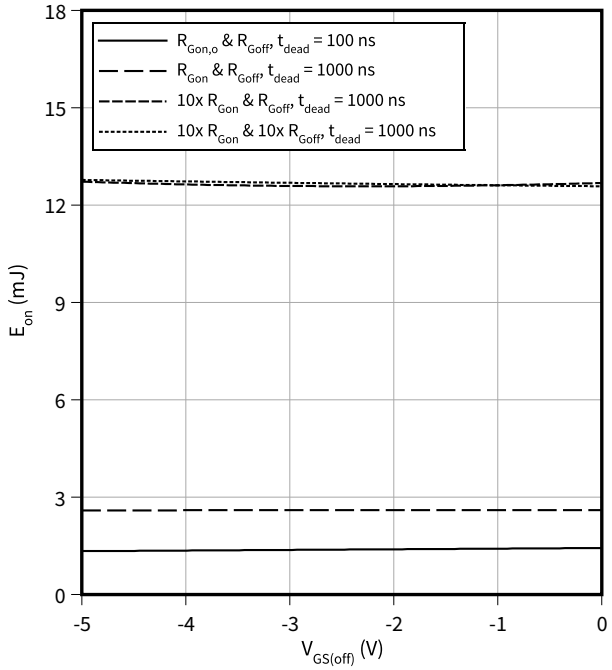
V_{DD} = 600 V, t_{dead} = 1000 ns, I_D = 150 A, V_{GS} = -3/18 V



Switching losses (typical), MOSFET

$E_{on} = f(V_{GS(off)})$

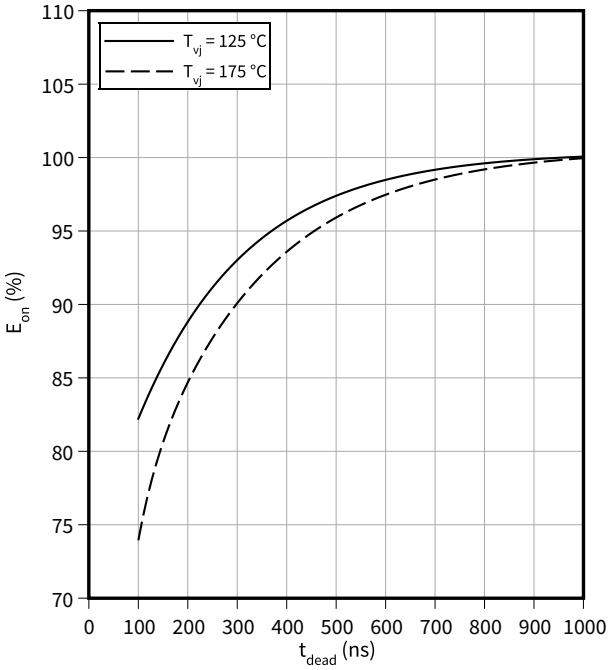
R_{Goff} = 0.51 Ω, V_{DD} = 600 V, R_{Gon} = 2.7 Ω, $V_{GS(on)}$ = 18 V, I_D = 150 A, $R_{Gon,o}$ = 1.5 Ω, T_{vj} = 175 °C



Switching losses (typical), MOSFET

$E_{on} = f(t_{dead})$

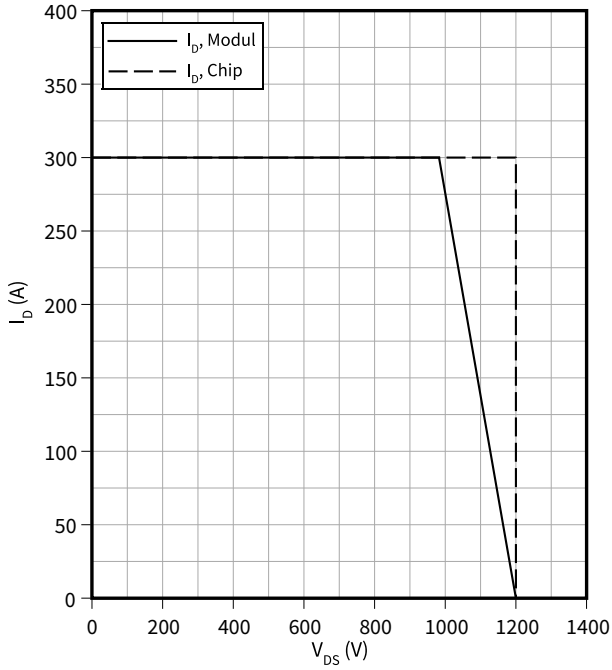
R_{Gon} = 2.7 Ω, I_D = 150 A, V_{DD} = 600 V, V_{GS} = -3/18 V



Reverse bias safe operating area (RBSOA), MOSFET

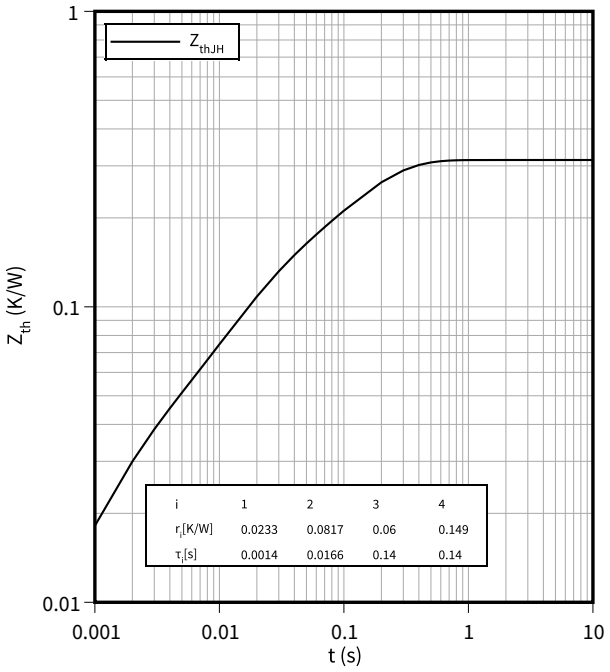
$I_D = f(V_{DS})$

R_{Goff} = 0.51 Ω, T_{vj} = 175 °C, V_{GS} = -3/18 V



Transient thermal impedance, MOSFET

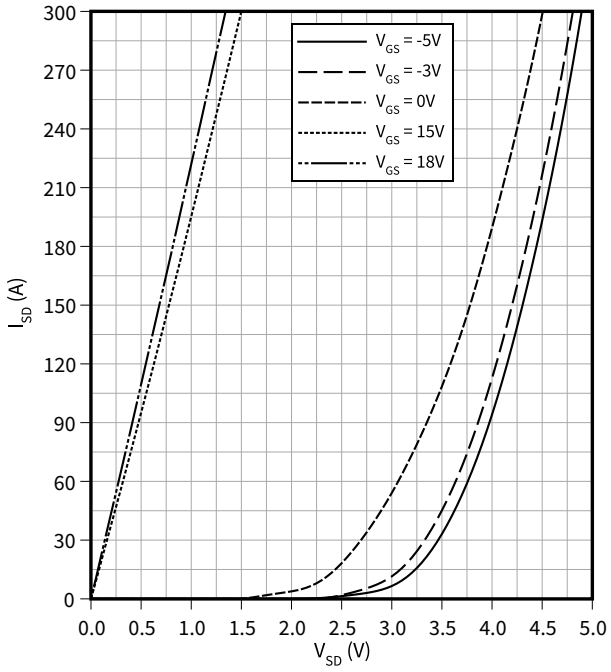
$Z_{th} = f(t)$



Forward characteristic body diode (typical), MOSFET

$I_{SD} = f(V_{SD})$

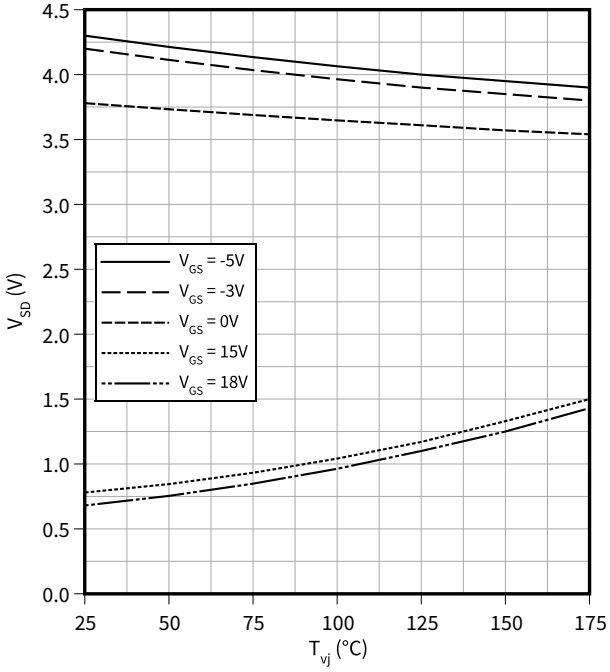
$T_{vj} = 25\ °C$



Forward voltage of body diode (typical), MOSFET

$V_{SD} = f(T_{vj})$

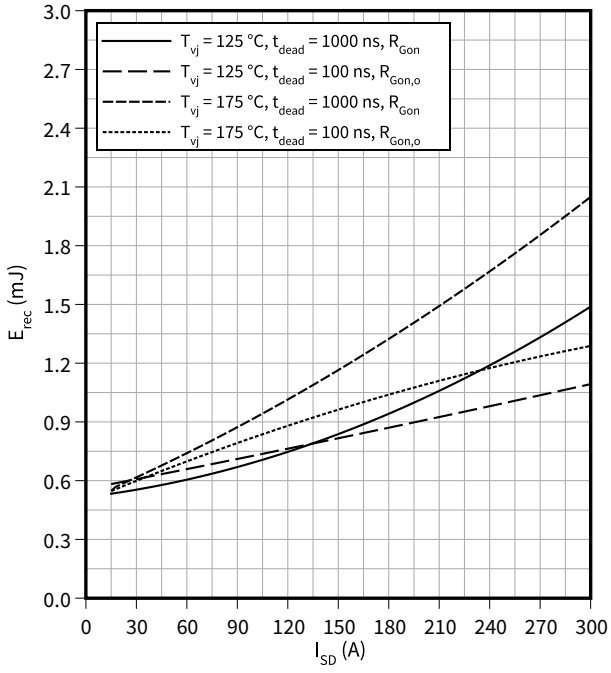
$I_{SD} = 150\ A$



Switching losses body diode (typical), MOSFET

$E_{rec} = f(I_{SD})$

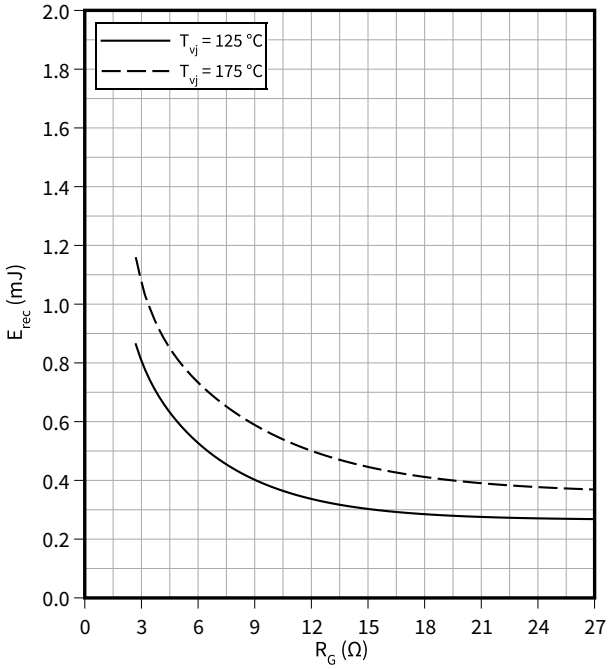
$R_{Gon} = 2.7\ \Omega$, $R_{Gon,o} = 1.5\ \Omega$, $V_{DD} = 600\ V$



Switching losses body diode (typical), MOSFET

$E_{rec} = f(R_G)$

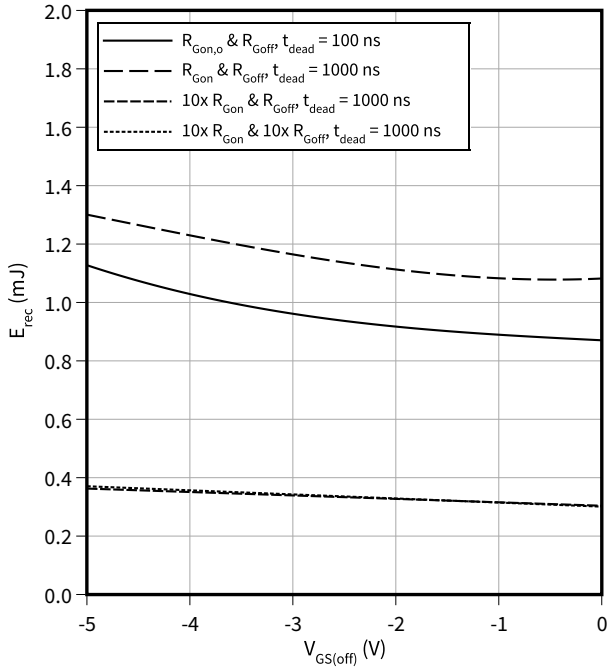
t_{dead} = 1000 ns, I_{SD} = 150 A, V_{DD} = 600 V



Switching losses body diode (typical), MOSFET

$E_{rec} = f(V_{GS(off)})$

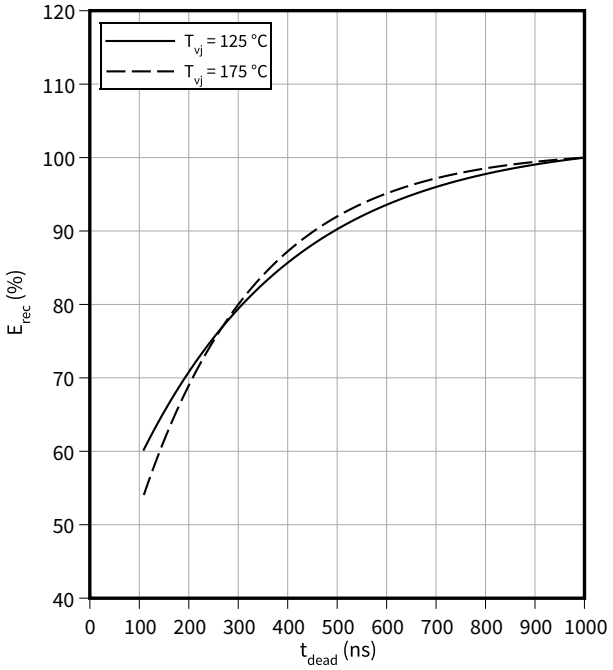
R_{Goff} = 0.51 Ω, R_{Gon} = 2.7 Ω, $V_{GS(on)}$ = 18 V, I_{SD} = 150 A, $R_{Gon,o}$ = 1.5 Ω, V_{DD} = 600 V, T_{vj} = 175 °C



Switching losses body diode (typical), MOSFET

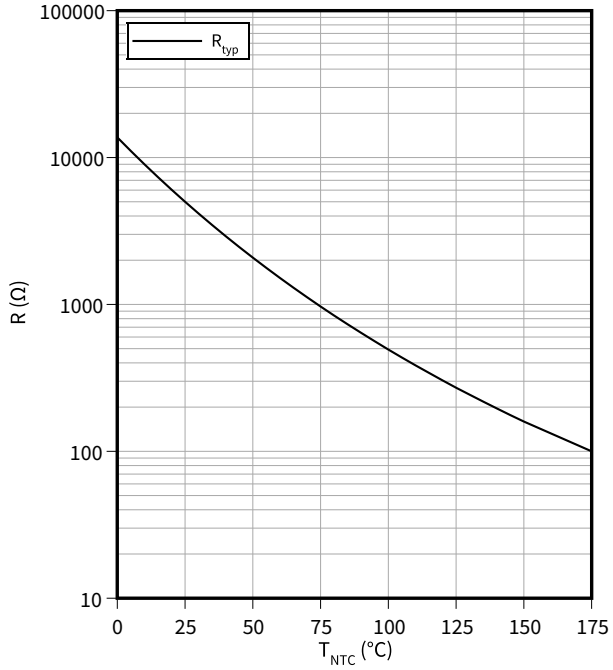
$E_{rec} = f(t_{dead})$

R_{Gon} = 2.7 Ω, I_D = 150 A, V_{DD} = 600 V, V_{GS} = -3/18 V



Temperature characteristic (typical), NTC-Thermistor

$R = f(T_{NTC})$



6 Circuit diagram

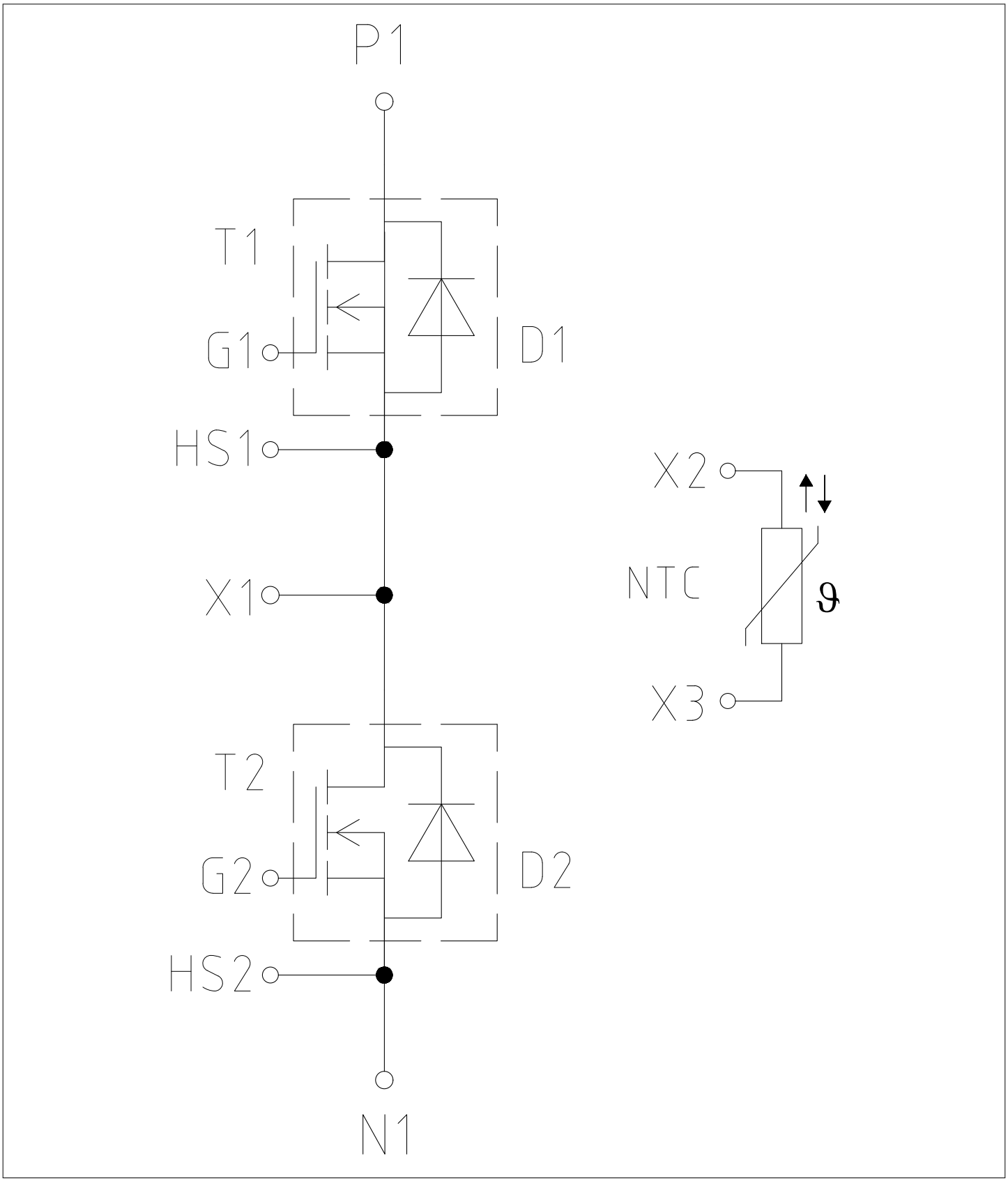


Figure 1

7 Package outlines

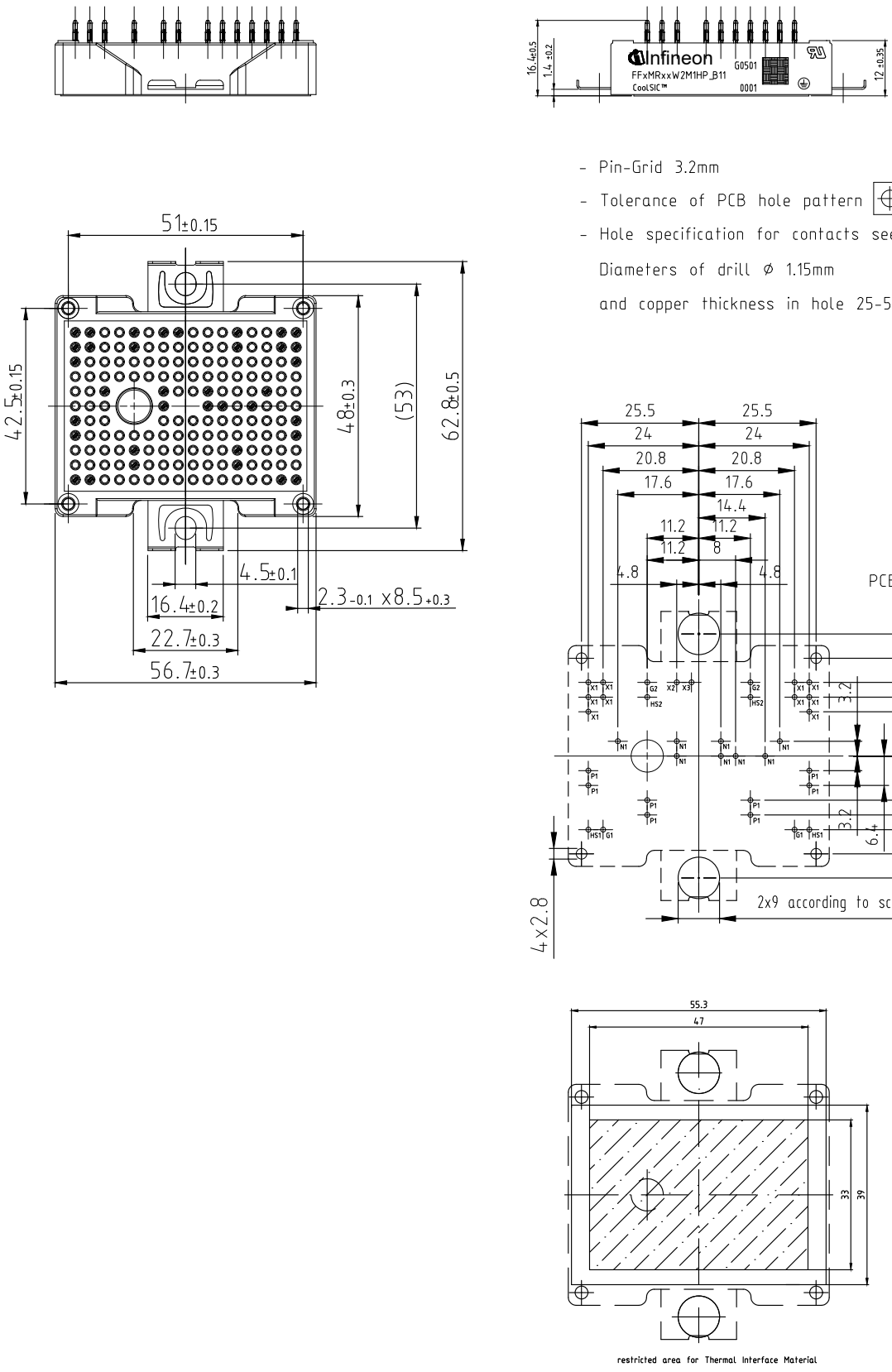


Figure 2

8 Module label code

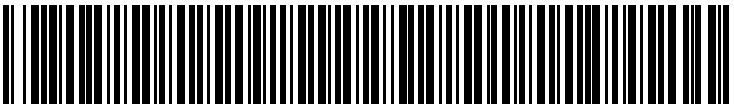
Module label code			
Code format	Data Matrix		Barcode Code128
Encoding	ASCII text		Code Set A
Symbol size	16x16		23 digits
Standard	IEC24720 and IEC16022		IEC8859-1
Code content	*Content* Module serial number Module material number Production order number Date code (production year) Date code (production week)	*Digit* 1 – 5 6 - 11 12 - 19 20 – 21 22 – 23	*Example* 71549 142846 55054991 15 30
Example	 7154914284655054991530	 7154914284655054991530	

Figure 3

Revision history

Document revision	Date of release	Description of changes
0.10	2023-08-07	Initial version
1.00	2025-03-14	Final datasheet

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